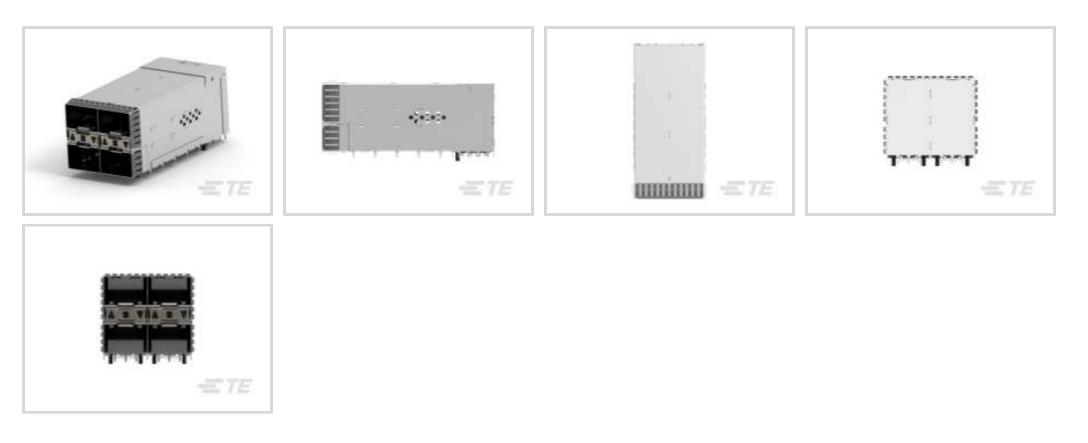
# 1-2198325-9 - ACTIVE

TE Internal #: 1-2198325-9 SFP, SFP+ & zSFP+, Cage Assembly with Integrated Connector, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, SFP+ Thermally Enhanced

#### View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > zSFP+ Stacked Cage Assembly: EMI Spring



Pluggable I/O Product Type: Cage Assembly with Integrated Connector

Data Rate (Max): 32 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Pluggable I/O Applications: SFP+ Thermally Enhanced

Lightpipe Options: With Lightpipe

All zSFP+ Stacked Cage Assembly: EMI Spring (45)



### Features

### **Product Type Features**

Form Factor	zSFP+ Stacked (SFP28)
Cage Type	Stacked
Pluggable I/O Product Type	Cage Assembly with Integrated Connector
Lightpipe Options	With Lightpipe
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Port Matrix Configuration	2 x 2
Lightpipe Configuration	Three
Lightpipe Style	Standard
Number of Ports	4
Number of Positions	80

SFP, SFP+ & zSFP+, Cage Assembly with Integrated Connector, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, SFP+ Thermally Enhanced



### **Electrical Characteristics**

Data Rate (Max)	32 Gb/s
Contact Features	
Tail Plating Material	Tin
Contact Mating Area Plating Material Thickness	.76 μm[29.92 μin]
Contact Mating Area Plating Material	Gold or Gold Flash over Palladium Nickel
Termination Features	
Termination Post & Tail Length	1.8 mm[.07 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Cage Material	Nickel Silver Alloy
Centerline (Pitch)	.8 mm[.032 in]
Dimensions	
PCB Thickness (Recommended)	1.5 mm[.059 in]

#### **Usage Conditions**

Operating	Temperature	Range
Operating	remperature	Range

### -55 – 105 °C[-67 – 221 °F]

### Operation/Application

Heat Sink Compatible	No
For Use With Pluggable I/O Products	zSFP+ SMT Connector
Pluggable I/O Applications	SFP+ Thermally Enhanced
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tray
Other	
EMI Containment Feature Type	Internal/External EMI Springs

### Product Compliance

For compliance documentation, visit the product page on TE.com>

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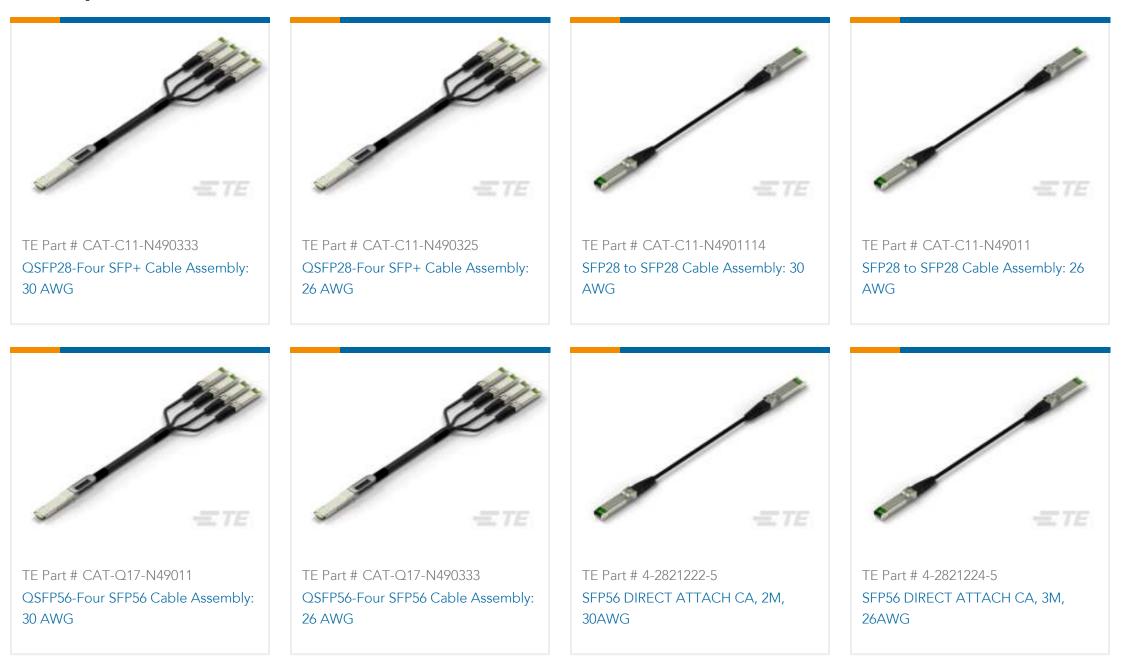


EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**



SFP, SFP+ & zSFP+, Cage Assembly with Integrated Connector, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, SFP+ Thermally Enhanced





# Customers Also Bought



CAGE ASSY, USFP-DD IXT, CUST HS	ZSFF
	LP, F

### Documents

**CAD** Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1-2198325-9\_B.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-2198325-9\_B.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-2198325-9\_B.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

zSFP+ Interconnect Brochure

English

SFP, SFP+ & zSFP+, Cage Assembly with Integrated Connector, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, SFP+ Thermally Enhanced



**Product Specifications** Application Specification

English

Product Environmental Compliance MD\_1-2198325-9\_11142018116\_dmtec English

MD\_1-2198325-9\_11142018116\_dmtec

English